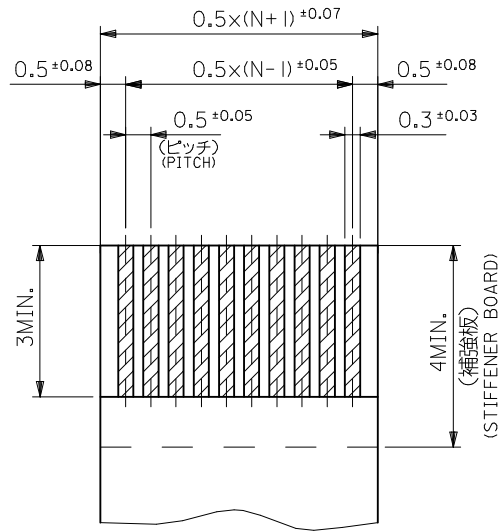
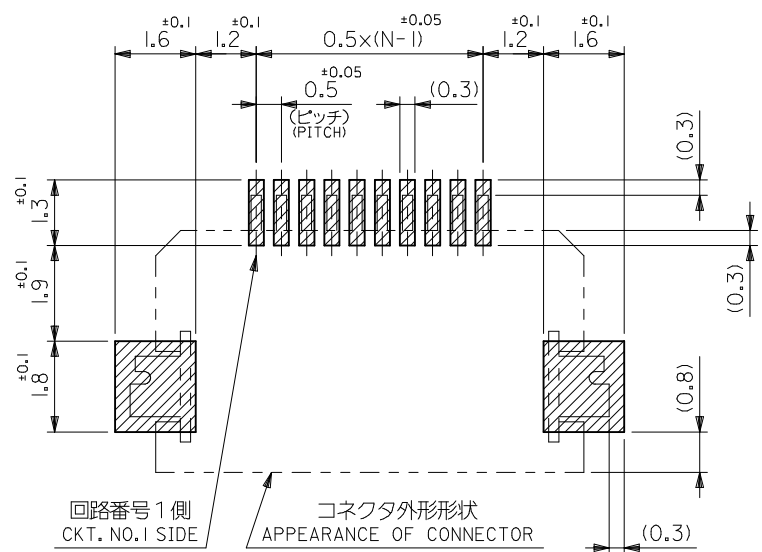


適合FPC推奨寸法
 APPLICABLE FPC
 RECOMMENDED DIMENSION
 (仕上がり厚さ: 0.3±0.03)
 (THICKNESS : 0.3±0.03)

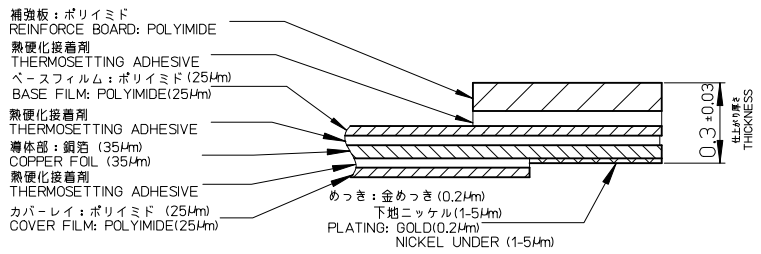


適合FFC推奨寸法
 APPLICABLE FFC
 RECOMMENDED DIMENSION
 (仕上がり厚さ: 0.3±0.03)
 (THICKNESS : 0.3±0.03)



推奨基板レイアウト
 RECOMMENDED P.C. BOARD
 PATTERN DIMENSION
 (マウント面)
 (MOUNTING SIDE)

マスク厚 : 100 μm
 マスク開口率: 100%
 SCREEN THICKNESS : 100MICROMETER
 SCREEN OPEN RATIO : 100%



FPC構成推奨仕様
 STRUCTURE OF FPC

FPC/FFCについて ABOUT FPC/FFC
 打ち抜き方向は導体側から補強板側を推奨します。
 導体側については数値が35 μmまたは50 μmを推奨します。
 RECOMMENDED PUNCHING DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER SIDE
 RECOMMENDED CONDUCTOR SPEC: SOFT COPPER FOIL
 RECOMMENDED CONDUCTOR THICKNESS: 35 MICROMETER OR 50 MICROMETER

FPCについて ABOUT FPC
 補強フィルム材質はポリイミドを推奨します。ベースフィルムは25 μmを推奨します。
 接着剤は熱硬化接着剤を推奨します。
 尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。
 RECOMMENDED STIFFENER MATERIAL: POLYIMIDE
 RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER
 RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE
 NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

REVISED EC NO: J2013-1133 DRWN: SANUMA 2013/04/11 CHKD: TAKAHASHI 2013/04/11 APPR: KMORIKAWA 2013/04/16 REV A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	52976-**-22	MODEL NO.
	10 UNDER	±0.2	DRAWN BY NKONDO	DATE 2012/09/18	TITLE 0.5MM FFC/FPC CONN NON-ZIF HSG ASSY (LOWER CONTACT)	THIRD ANGLE PROJECTION	
	10 OVER 30 UNDER	±0.25	CHECKED BY KTAKAHASHI	DATE 2012/09/18			
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2013/03/15			
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		DOCUMENT NO. SD-52976-016	SHEET NO. 2 OF 2
SIZE A3				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			